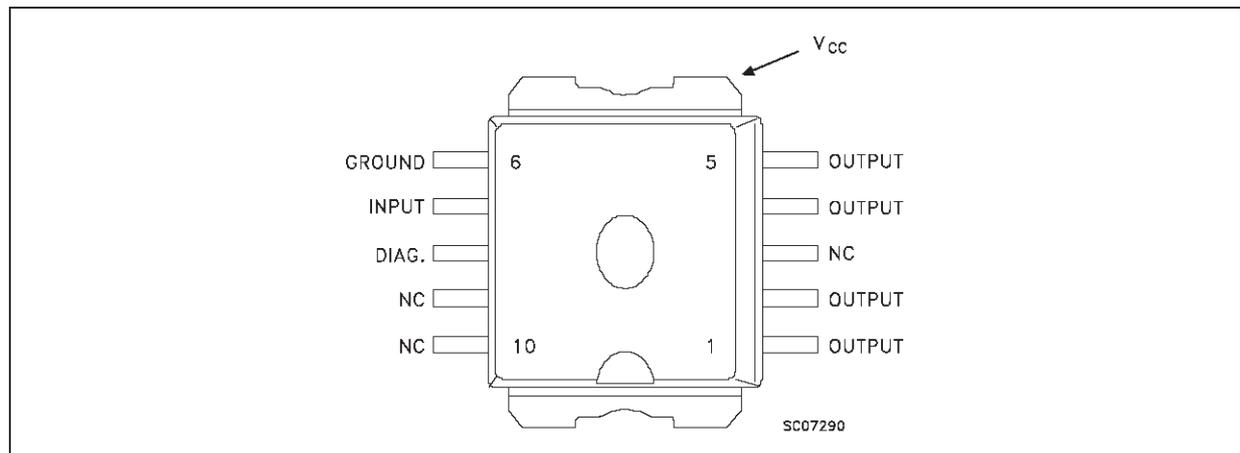


VN16BSP

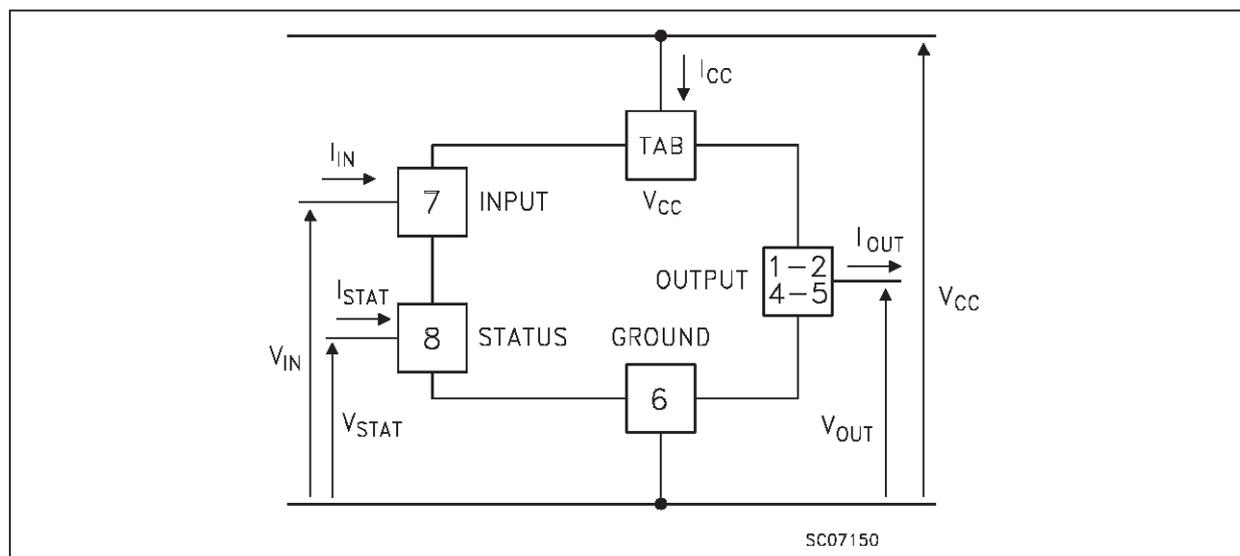
ABSOLUTE MAXIMUM RATING

Symbol	Parameter	Value	Unit
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	40	V
I_{OUT}	Output Current (cont.) at $T_c = 85\text{ }^\circ\text{C}$	20	A
$I_{OUT(RMS)}$	RMS Output Current at $T_c = 85\text{ }^\circ\text{C}$	20	A
I_R	Reverse Output Current at $T_c = 85\text{ }^\circ\text{C}$ ($f > 1\text{Hz}$)	-20	A
I_{IN}	Input Current	± 10	mA
$-V_{CC}$	Reverse Supply Voltage	-4	V
I_{STAT}	Status Current	± 10	mA
V_{ESD}	Electrostatic Discharge (1.5 k Ω , 100 pF)	2000	V
P_{tot}	Power Dissipation at $T_c = 25\text{ }^\circ\text{C}$	82	W
T_j	Junction Operating Temperature	-40 to 150	$^\circ\text{C}$
T_{stg}	Storage Temperature	-55 to 150	$^\circ\text{C}$

CONNECTION DIAGRAMS



CURRENT AND VOLTAGE CONVENTIONS



THERMAL DATA

R _{thj-case}	Thermal Resistance Junction-case	Max	1.5	°C/W
R _{thj-amb}	Thermal Resistance Junction-ambient (\$)	Max	50	°C/W

(\$) When mounted using minimum recommended pad size on FR-4 board

ELECTRICAL CHARACTERISTICS (8 < V_{CC} < 16 V; -40 ≤ T_j ≤ 125 °C unless otherwise specified)

POWER

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{CC}	Supply Voltage		6	13	26	V
I _n (*)	Nominal Current	T _c = 85 °C V _{DS(on)} ≤ 0.5 V _{CC} = 13 V	5.6		8.8	A
R _{on}	On State Resistance	I _{OUT} = I _n V _{CC} = 13 V T _j = 25 °C	0.038		0.06	Ω
I _s	Supply Current	Off State V _{CC} = 13 V T _j ≥ 25 °C		25	50	μA
V _{DS(MAX)}	Maximum Voltage Drop	I _{OUT} = 20 A V _{CC} = 13 V T _c = 85 °C	1		1.8	V
R _i	Output to GND Internal Impedance	T _j = 25 °C	5	10	20	KΩ

SWITCHING

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
t _{d(on)} (^)	Turn-on Delay Time Of Output Current	R _{load} = 1.6 Ω	5	50	500	μs
t _r (^)	Rise Time Of Output Current	R _{load} = 1.6 Ω	40	100	680	μs
t _{d(off)} (^)	Turn-off Delay Time Of Output Current	R _{load} = 1.6 Ω	10	100	500	μs
t _f (^)	Fall Time Of Output Current	R _{load} = 1.6 Ω	40	100	680	μs
(di/dt) _{on}	Turn-on Current Slope	R _{load} = 1.6 Ω V _{CC} = 13 V	0.008		0.1	A/μs
(di/dt) _{off}	Turn-off Current Slope	R _{load} = 1.6 Ω V _{CC} = 13 V	0.008		0.1	A/μs
V _{demag}	Inductive Load Clamp Voltage	R _{load} = 1.6 Ω L = 1 mH	-24	-18	-14	V

LOGIC INPUT

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{IL}	Input Low Level Voltage				1.5	V
V _{IH}	Input High Level Voltage		3.5		(•)	V
V _{I(hyst.)}	Input Hysteresis Voltage		0.2	1	1.5	V
I _{IN}	Input Current	V _{IN} = 5 V T _j = 25 °C			100	μA
V _{ICL}	Input Clamp Voltage	I _{IN} = 10 mA I _{IN} = -10 mA	5	6 -0.7	7	V V

ELECTRICAL CHARACTERISTICS (continued)
PROTECTION AND DIAGNOSTICS (continued)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{STAT}	Status Voltage Output Low	I _{STAT} = 1.6 mA			0.4	V
V _{USD}	Under Voltage Shut Down		3.5	5	6	V
V _{SCL}	Status Clamp Voltage	I _{STAT} = 10 mA I _{STAT} = -10 mA	5	6 -0.7	7	V V
T _{TSD}	Thermal Shut-down Temperature		140	160	180	°C
T _{SD(hyst.)}	Thermal Shut-down Hysteresis			15	50	°C
T _R	Reset Temperature		125			°C
V _{OL}	Open Voltage Level	Off-State (note 2)	2.5	3.8	5	V
I _{OL}	Open Load Current Level	On-State	0.15		0.85	A
t _{povl}	Status Delay	(note 3)		5	10	µs
t _{pol}	Status Delay	(note 3)	50	400	2500	µs

(*) I_n= Nominal current according to ISO definition for high side automotive switch (see note 1)

(^) See Switching Time Waveforms

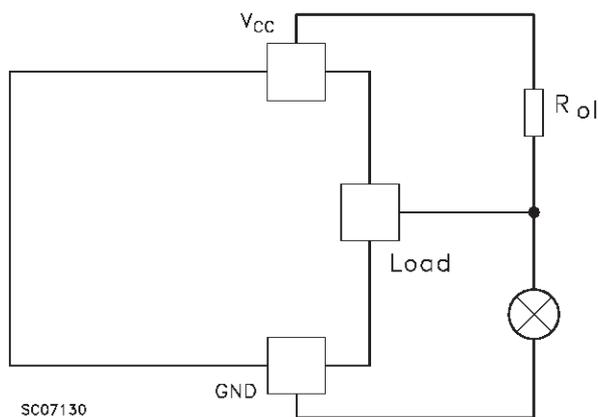
(•) The V_H is internally clamped at 6V about. It is possible to connect this pin to an higher voltage via an external resistor calculated to not exceed 10 mA at the input pin.

note 1: The Nominal Current is the current at T_c = 85 °C for battery voltage of 13V which produces a voltage drop of 0.5 V

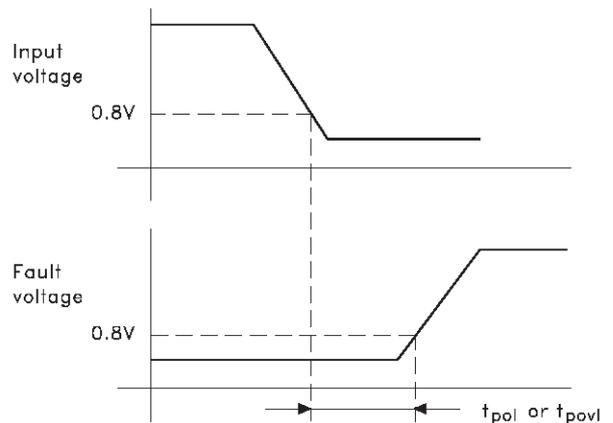
note 2: I_{OL(off)} = (V_{CC} -V_{OL})/R_{OL} (see figure)

note 3: t_{povl} t_{pol}: ISO definition (see figure)

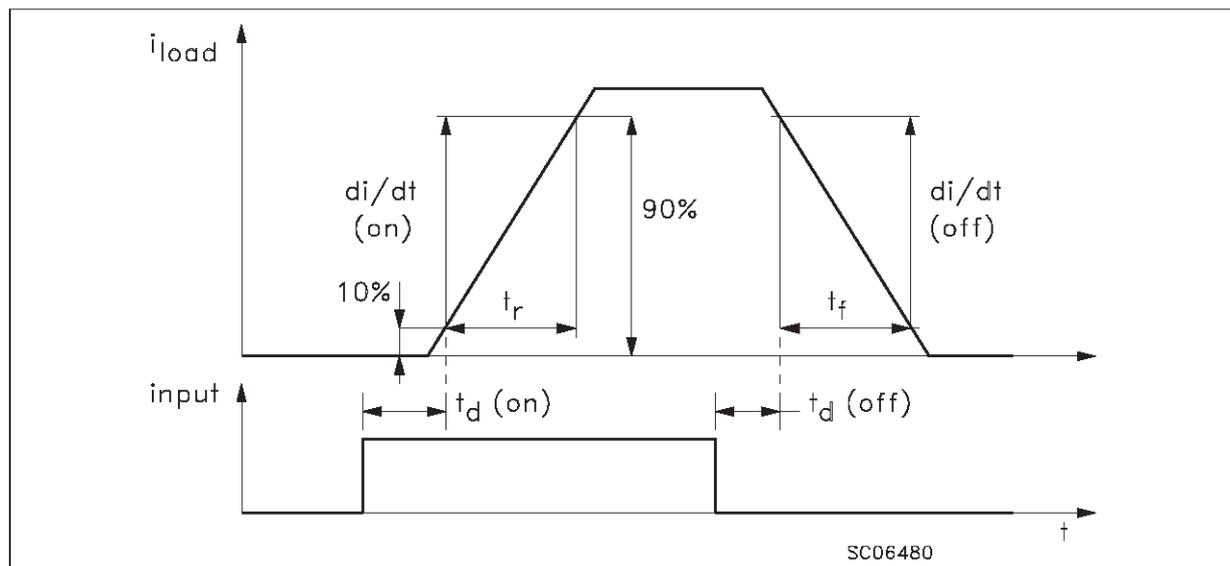
Note 2 Relevant Figure



Note 3 Relevant Figure



Switching Time Waveforms

**FUNCTIONAL DESCRIPTION**

The device has a diagnostic output which indicates open load in on-state, open load in off-state, over temperature conditions and stuck-on to V_{CC} .

From the falling edge of the input signal, the status output, initially low to signal a fault condition (overtemperature or open load on-state), will go back to a high state with a different delay in case of overtemperature ($tpovl$) and in case of open load ($tpol$) respectively. This feature allows to discriminate the nature of the detected fault. To protect the device against short circuit and over current condition, the thermal protection turns the integrated Power MOS off at a minimum junction temperature of $140\text{ }^{\circ}\text{C}$. When this temperature returns to $125\text{ }^{\circ}\text{C}$ the switch is automatically turned on again. In short circuit the protection reacts with virtually no delay, the sensor being located inside the Power MOS area. An internal function of the devices ensures the fast demagnetization of inductive loads with a typical voltage (V_{demag}) of -18V . This function allows to greatly reduce the power dissipation according to the formula:

$$P_{dem} = 0.5 \cdot L_{load} \cdot (I_{load})^2 \cdot [(V_{CC} + V_{demag}) / V_{demag}] \cdot f$$

where f = switching frequency and V_{demag} = demagnetization voltage.

The maximum inductance which causes the chip

temperature to reach the shut-down temperature in a specified thermal environment is a function of the load current for a fixed V_{CC} , V_{demag} and f according to the above formula. In this device if the GND pin is disconnected, with V_{CC} not exceeding 16V , it will switch off.

PROTECTING THE DEVICE AGAINST REVERSE BATTERY

The simplest way to protect the device against a continuous reverse battery voltage (-26V) is to insert a Schottky diode between pin 1 (GND) and ground, as shown in the typical application circuit (fig.3).

The consequences of the voltage drop across this diode are as follows:

If the input is pulled to power GND, a negative voltage of $-V_f$ is seen by the device. (V_{il} , V_{ih} thresholds and V_{stat} are increased by V_f with respect to power GND).

The undervoltage shutdown level is increased by V_f .

If there is no need for the control unit to handle external analog signals referred to the power GND, the best approach is to connect the reference potential of the control unit to node [1] (see application circuit in fig. 3), which becomes the common signal GND for the whole control board avoiding shift of V_{ih} , V_{il} and V_{stat} . This solution allows the use of a standard diode.

TRUTH TABLE

	INPUT	OUTPUT	DIAGNOSTIC
Normal Operation	L	L	H
	H	H	H
Over-temperature	X	L	L
Under-voltage	X	L	H
Short load to V _{CC}	H	H	L
	L	H	L
Open Load	H	H	L
	L	L	L (#)

(#) With an additional external resistor

Figure 1: Waveforms

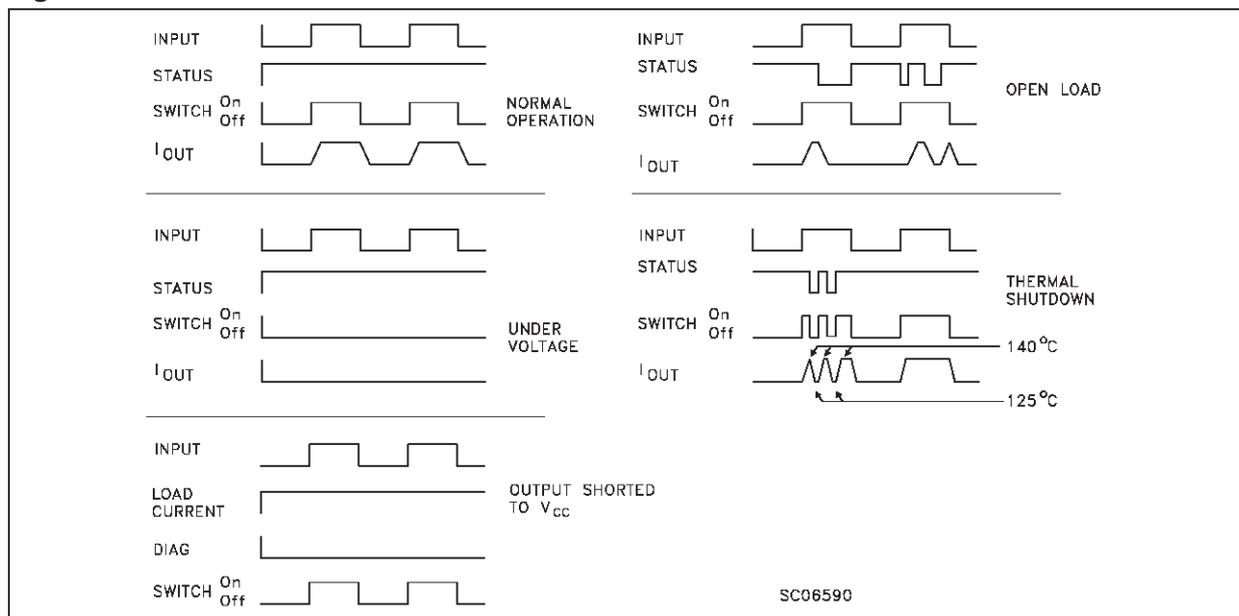


Figure 2: Over Current Test Circuit

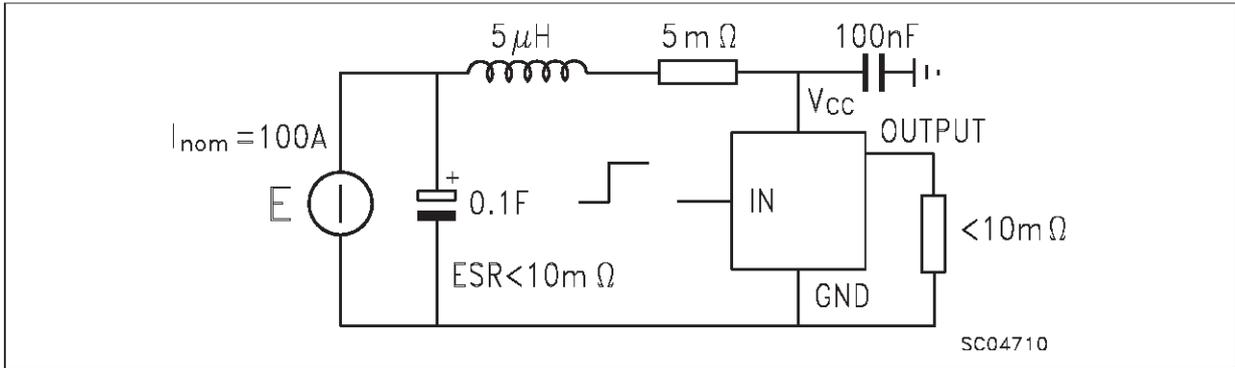


Figure 3: Typical Application Circuit With A Schottky Diode For Reverse Supply Protection

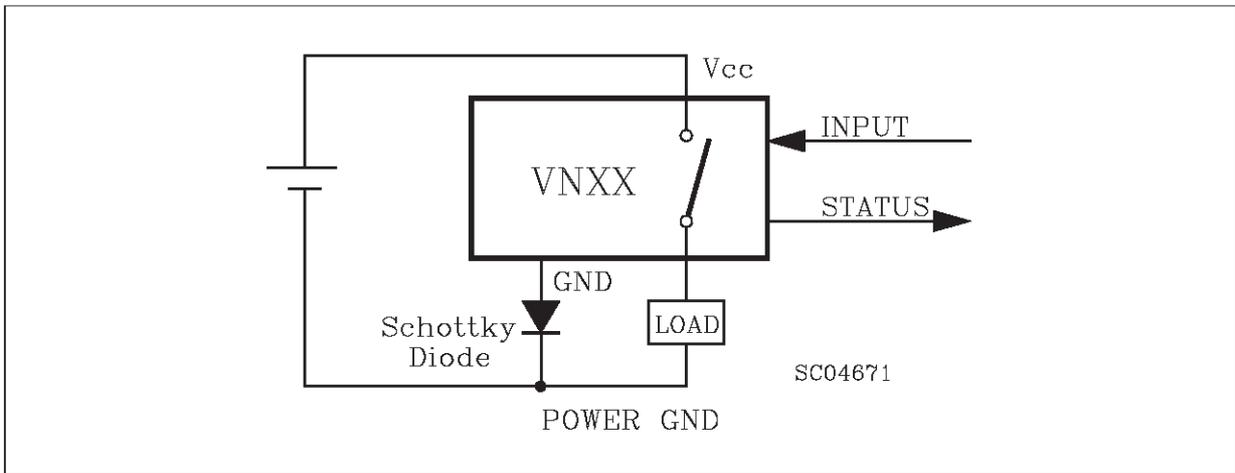
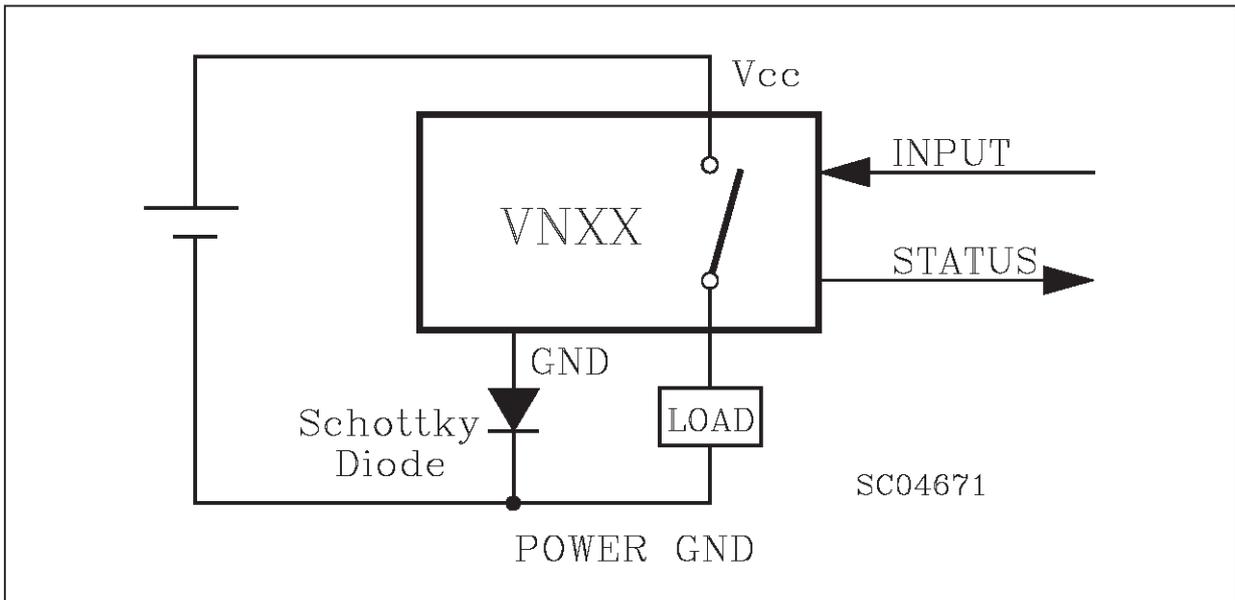
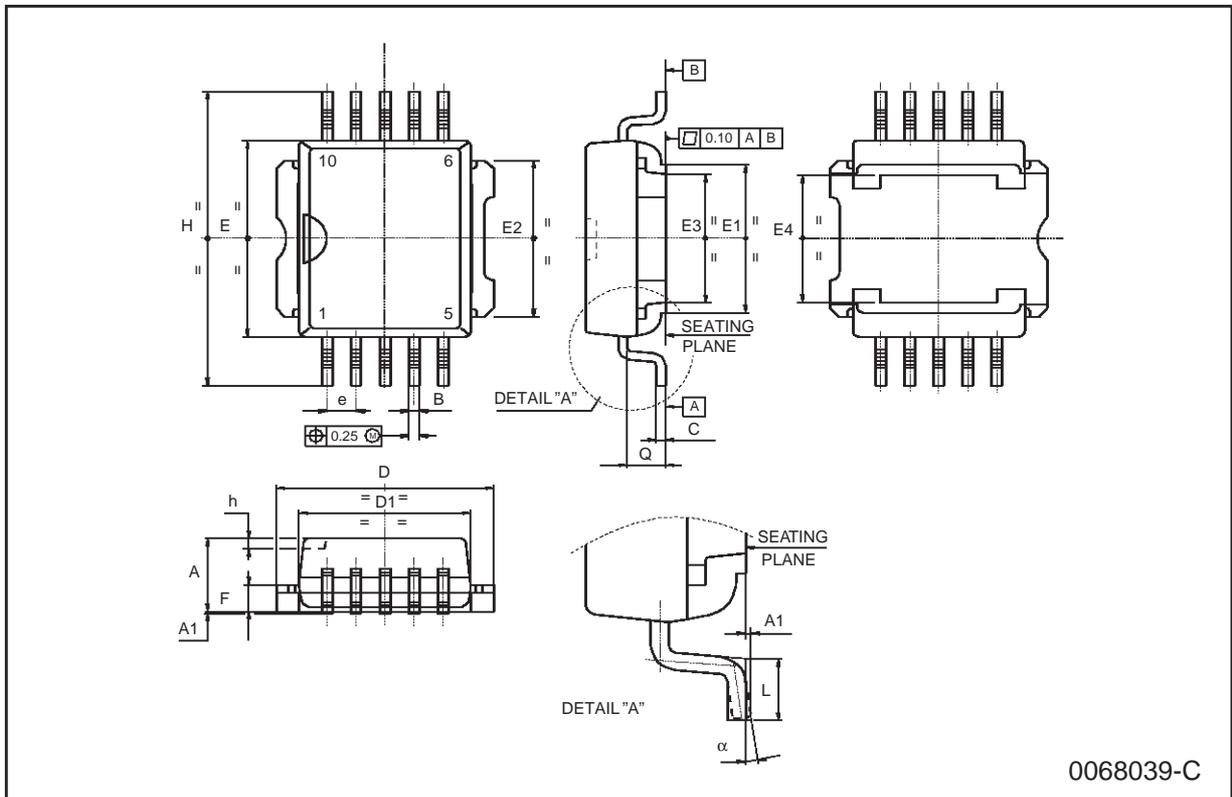


Figure 4: Typical Application Circuit With Separate Signal Ground



Power SO-10 MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	3.35		3.65	0.132		0.144
A1	0.00		0.10	0.000		0.004
B	0.40		0.60	0.016		0.024
c	0.35		0.55	0.013		0.022
D	9.40		9.60	0.370		0.378
D1	7.40		7.60	0.291		0.300
E	9.30		9.50	0.366		0.374
E1	7.20		7.40	0.283		0.291
E2	7.20		7.60	0.283		0.300
E3	6.10		6.35	0.240		0.250
E4	5.90		6.10	0.232		0.240
e		1.27			0.050	
F	1.25		1.35	0.049		0.053
H	13.80		14.40	0.543		0.567
h		0.50			0.002	
L	1.20		1.80	0.047		0.071
q		1.70			0.067	
α	0°		8°			



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